

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

RB521S30T1G(MS)

Product specification

Features

- UltraSmallmoldtype.(SOD-523)
- LowIR
- Highreliability.

Applications

- Lowcurrentrectification


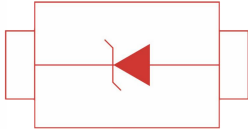

Construction

- Silicon epitaxial planar

Mechanical Characteristics

- Leadfinish:100%matteSn(Tin)
- Mountingposition:Any
- Qualifiedmaxreflowtemperature:260°C
- DevicemeetsMSL1requirements
- Puretinplating:7~17um
- Pinflatness:≤3mil

Reference News

Outline	Pin Configuration	Marking
		
SOD-523		

Electrical characteristics per line @25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	-	-	0.5	V	$I_F=200\text{mA}$
Reverse current	I_R	-	-	30	μA	$V_R=10\text{V}$

Absolute maximum rating @25°C

Parameter	Symbol	limits	Unit
Reverse voltage (DC)	V_{RM}	30	V
Average rectified forward current	I_b	200	mA
Forward current surge peak (60Hz 1cyc)	I_{FSM}	1	A
Operating Junction temperature Range	T_j	-55 to 125	°C
Storage temperature	T_{stg}	-40 to +125	°C

Typical Characteristics

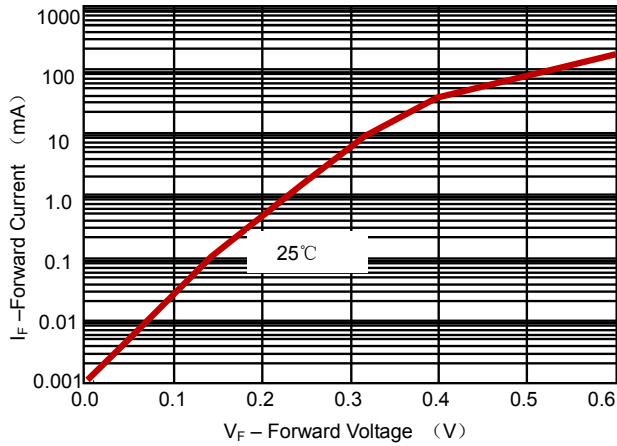


Fig 1. Forward Voltage

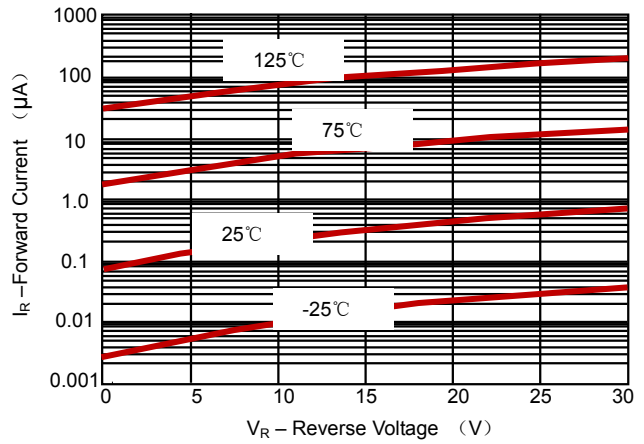


Fig 2. Leakage Current

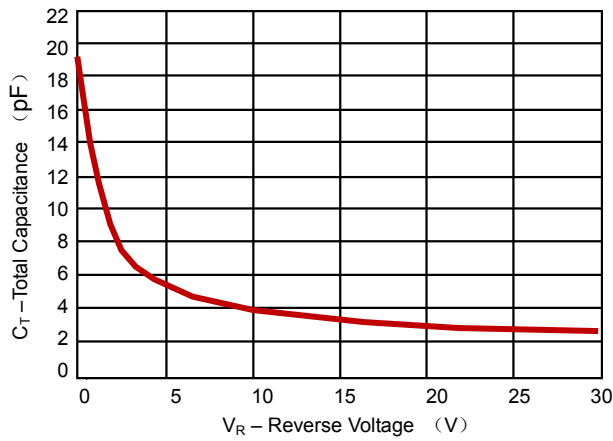
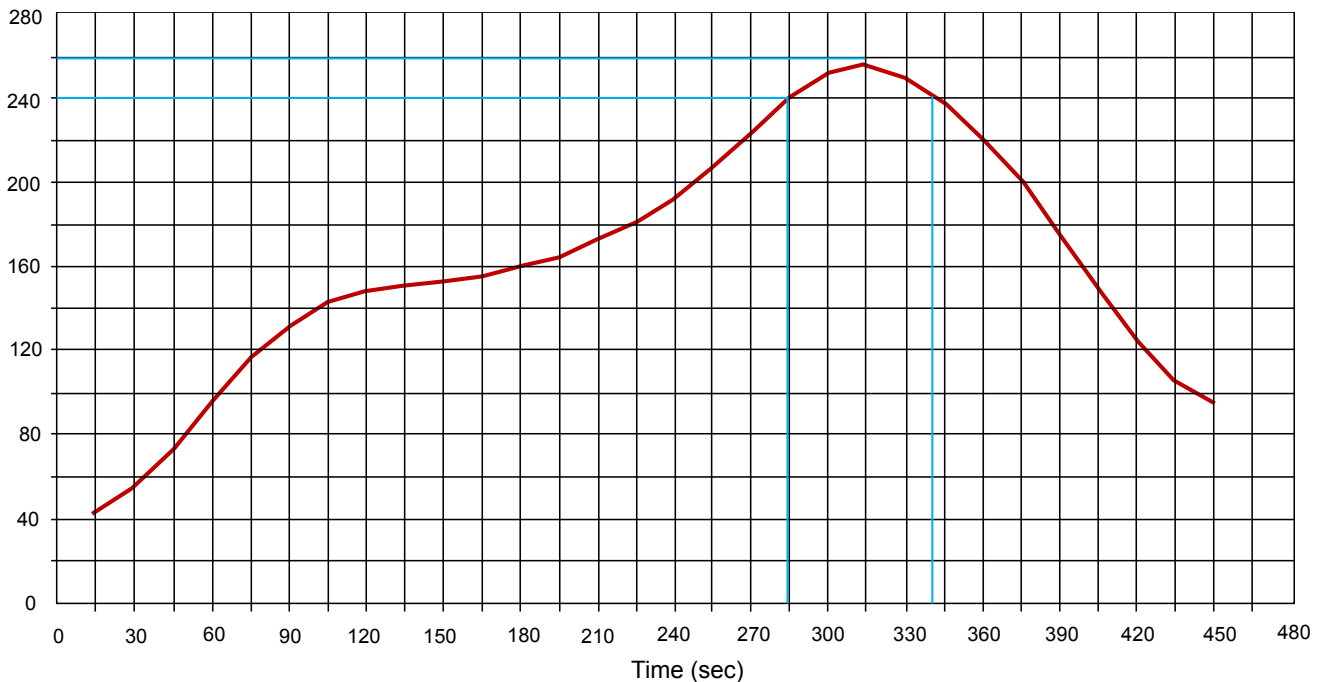


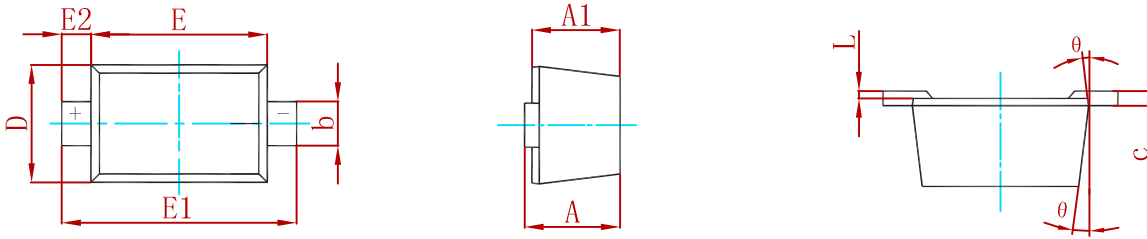
Fig 3. Total Capacitance

Solder Reflow Recommendation

Peak Temp=257°C, Ramp Rate=0.802deg. °C/sec

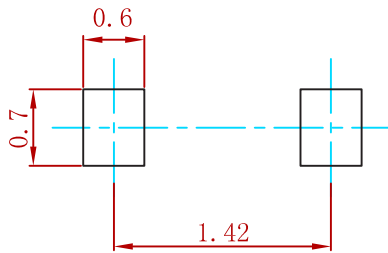


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RB521S30T1G(MS)	SOD-523	3000

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